NOTES (UNLESS OTHERWISE SPECIFIED):

1. THIS DRAWING SPECIFIES THE REQUIREMENTS FOR A PRINTED WIRING BOARD IN ACCORDANCE WITH SPECIFICATION IPC-A-600 CLASS 2 (LATEST REVISION).

2. THE PWB MUST BE LEAD FREE ASSEMBLY PROCESS COMPATIBLE AND MUST BE ABLE TO HANDLE A MINIMUM OF 5 CYCLES AT 260 DEGREES CELSIUS FOR 10 SECONDS.

3. BASE MATERIAL - LAMINATE AND PREPREG SHALL MEET IPC-4101B-26, 83 or 98
   Tg - MUST BE GREATER THAN OR EQUAL TO 150 DEGREES CELSIUS.
   Td - MUST BE GREATER THAN OR EQUAL TO 330 DEGREES CELSIUS.
   Er - MUST BE FROM 4.2 TO 4.4

4. COPPER FOIL WEIGHT - SEE STACKUP DETAIL 'A'

5. CHARACTERISTIC IMPEDANCE - NONE

6. MINIMUM CONDUCTIVE WIDTH/SPACING TO BE .006"/.005"

7. PLATING FINISH - BOTH SIDES ENIG (ELECTROLESS NICKEL IMMERSION GOLD):
   .05080-.232 MICRON (2-8 MICROINCH) OF GOLD OVER
   2.540-6.350 MICRON (100-250 MICROINCH) OF NICKEL.

△8 ALL THROUGH HOLE VIAS MAY BE PLATED SHUT.

9. SOLDERMASK - RED COLOR BOTH SIDES.
   MODIFICATION OF SOLDERMASK IS NOT ALLOWED WITHOUT WRITTEN PERMISSION FROM NXP.

10. SILKSCREEN - WHITE EPOXY INK, BOTH SIDES. NO SILK ON PADS.

11. ELECTRICAL TEST - 100% IPCD356.

12. PRINTED WIRING BOARD IS TO BE INDIVIDUALLY BAGGED.

13. DRC'S MUST BE RUN ON THE GERBER BEFORE BUILDING BOARDS, UNLESS PRIOR APPROVAL IS GIVEN IN WRITING BY FREESCALE.

14. TEARDROPS MAYBE ADDED AT THE FAB HOUSE TO ALL SIGNAL LAYERS.

15. 2 SOLDER SAMPLES TO BE PROVIDED.

△16 BASIC GRID INCREMENT AT 1:1 IS .0001.

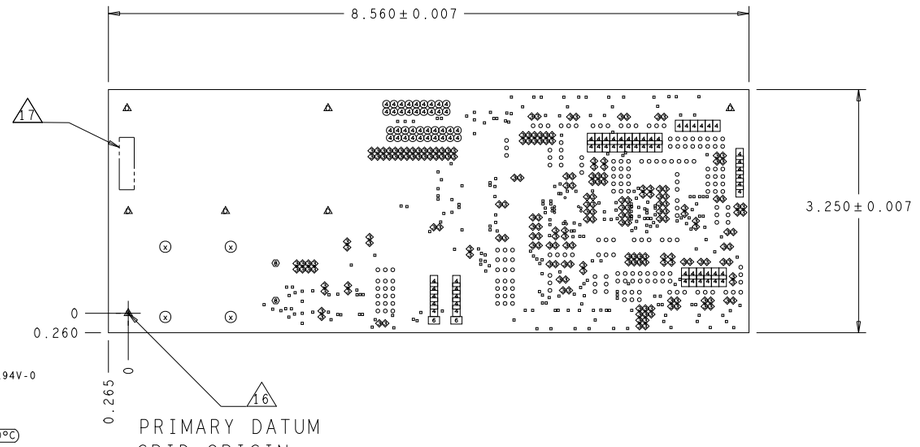
△17 SUPPLIER MARKINGS - ON SOLDER SIDE ONLY, WHERE SHOWN.
   - MUST BE UL RECOGNIZED AND MUST HAVE AN ID THAT CONFORMS TO UL94V-0

18. THE PWB WILL BE MARKED AS LEAD FREE BY USE OF AN INK STAMP (pb)

19. THE PWB WILL BE MARKED AS LEAD FREE PROCESS COMPATIBLE BY USE OF AN INK STAMP (260°C)

20. ALL PLATED AND NON-PLATED THROUGH HOLES ARE TO BE DRILLED AT PRIMARY DRILL STEP. ALL HOLE LOCATION TOLERANCES ARE TO BE +/-.002 IN REFERENCE TO THE PRIMARY DATUM.

21. FINISHED PCB MUST BE PANELIZED FOR ASSEMBLY ACCORDING TO CONTRACT MANUFACTURERS REQUIREMENTS. THE ADDITION OF RAILS AND .125" NON-PLATED TOOLING HOLES ARE AT THE DISCRETION OF CONTRACT MANUFACTURER.PANELIZATION MUST BE APPROVED BY CONTRACT MANUFACTURER.

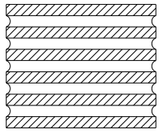


REVISIONS				
ZONE	REV	DESCRIPTION	DATE	APPROVED
	A	ORIGINAL RELEASE	12-18-15	X.X.
	B	COMPATIBILITY MRB/FRDM+LAYOUT REVIEW (ADC)	03-12-16	X.X.

8

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
□	10.0	+0.0/-10.0	PLATED	262
○	12.0	+0.0/-12.0	PLATED	11
◈	35.0	+2.0/-2.0	PLATED	208
○	40.0	+3.0/-3.0	PLATED	189
④	40.0	+3.0/-3.0	PLATED	38
+	41.0	+3.0/-3.0	PLATED	54
6	62.0	+3.0/-3.0	PLATED	2
⑧	86.0	+3.0/-3.0	PLATED	2
△	125.0	+3.0/-3.0	NON-PLATED	7
⊗	130.0	+2.0/-2.0	NON-PLATED	4

FINISHED Cu WEIGHT



0.062 +/- 10%	LAYER 1	COMPONENT SIDE	1/2 to 1 oz.
	LAYER 2	GROUND PLANE	1 oz.
	LAYER 3	INTERNAL 1	1/2 oz.
	LAYER 4	INTERNAL 2	1/2 oz.
	LAYER 5	POWER PLANE	1 oz.
	LAYER 6	SOLDER SIDE	1/2 to 1 oz.

DETAIL A
LAYER STACKUP
SCALE: NONE

--- PUBI (PUBLIC INFORMATION)
X IUO (NXP INTERNAL USE ONLY)
--- CP (NXP CONFIDENTIAL PROPRIETARY)

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
DECIMALS ANGLES
.XX .01 .0-30'
.XXX .005
✓ RMS ALL MACHINED SURFACES
BREAK ALL SHARP EDGES AND CORNERS.
REMOVE BURRS.
UNDERLINED DIM. NOT TO SCALE.
THIRD ANGLE ORTHOGRAPHIC PROJECTION IS USED.

APPROVALS	DATE
DRAWN: neuronPro-RCC02C	03-12-16
CHECKED: ANDREW MACDONALD	03-12-16
DESIGN ENGINEER: PASCAL BERNARD	03-12-16

PART NO. 170-29153

NXP SEMICONDUCTORS
6501 WILLIAM CANNON DRIVE WEST AUSTIN, TEXAS 78735 USA

TITLE: PRINTED WIRING BOARD
FRDM-SENSORS-LF

SIZE	CAD FILE NAME	DWG. NO.	REV
D	LAY-29153	FAB-29153	B

SCALE 1/1 DO NOT SCALE DRAWING SHEET 1 OF 1